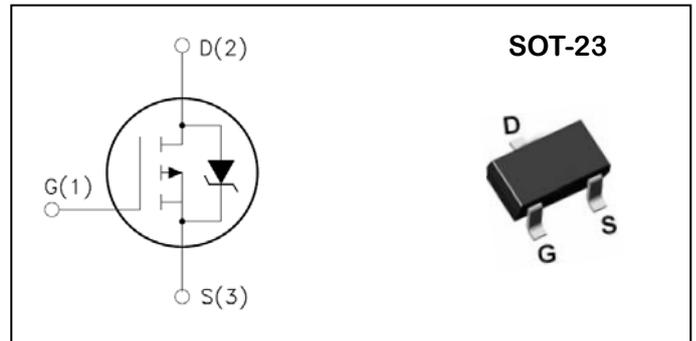


## P-Channel Enhancement Mode Field Effect Transistor

### PRODUCT SUMMARY

$V_{DSS}$	$I_D$	$R_{DS(ON)}$ (m $\Omega$ )
-40V	-5A	70m $\Omega$



### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise specified )

Symbol	Parameter		Ratings	Unit
<b>Common Ratings</b>				
$V_{DSS}$	Drain-Source Voltage		-40	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	
$T_J$	Maximum Junction Temperature		150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		-55 to 150	$^\circ\text{C}$
$I_S$	Diode Continuous Forward Current (3)	$T_C=25^\circ\text{C}$	-1.5	A
<b>Mounted on Large Heat Sink</b>				
$I_{DM}$	300 $\mu\text{s}$ Pulse Drain Current Tested(1)	$T_C=25^\circ\text{C}$	-15	A
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$	-5	A
$P_D$	Maximum Power Dissipation (3)		1.4	W

1. Pulse width limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{thJA}$	Thermal resistance junction-ambient max (3)	89	$^\circ\text{C/W}$

## Electrical Characteristics (T<sub>A</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
<b>On/off Characteristics</b>						
B <sub>VDS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250uA	-40	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 40V, V <sub>GS</sub> =0V	--	--	1	uA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA	-1.1	-1.65	-2.3	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> = ± 20V, V <sub>DS</sub> =0V	--	--	± 100	nA
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance <sup>(2)</sup>	V <sub>GS</sub> = -10V, I <sub>DS</sub> =-3A	--	70	85	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>DS</sub> =-2A	--	95	120	
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> = -20V, Frequency=1.0MHz	--	600	--	pF
C <sub>oss</sub>	Output Capacitance					
C <sub>riss</sub>	Reverse Transfer Capacitance					
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time <sup>(1)</sup>	V <sub>DD</sub> =-20V, I <sub>D</sub> =-3A, V <sub>GS</sub> =-10V, R <sub>GEN</sub> =3 Ω	--	9	--	ns
t <sub>r</sub>	Turn-on Rise Time <sup>(1)</sup>					
t <sub>d(OFF)</sub>	Turn-off Delay Time <sup>(1)</sup>					
t <sub>f</sub>	Turn-off Fall Time <sup>(1)</sup>					
Q <sub>g</sub>	Total Gate Charge <sup>(1)</sup>	V <sub>DS</sub> =-20V, V <sub>GS</sub> = -10V, I <sub>DS</sub> =-3A	--	14	--	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>(1)</sup>					
Q <sub>gd</sub>	Gate-Drain Charge <sup>(1)</sup>					
<b>Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>(2)</sup>	I <sub>SD</sub> = -5A, V <sub>GS</sub> = 0	--	--	-1.2	V

### NOTES:

1. Independent of operating temperature.
2. Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2%
3. Surface Mounted on FR4 Board, t < 10 sec.

## Typical Performance Characteristics

Figure 1: Output Characteristics

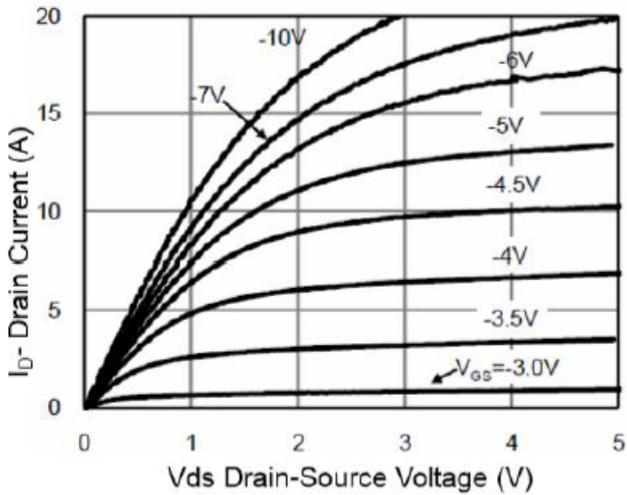


Figure 2: Source-Drain Diode Forward

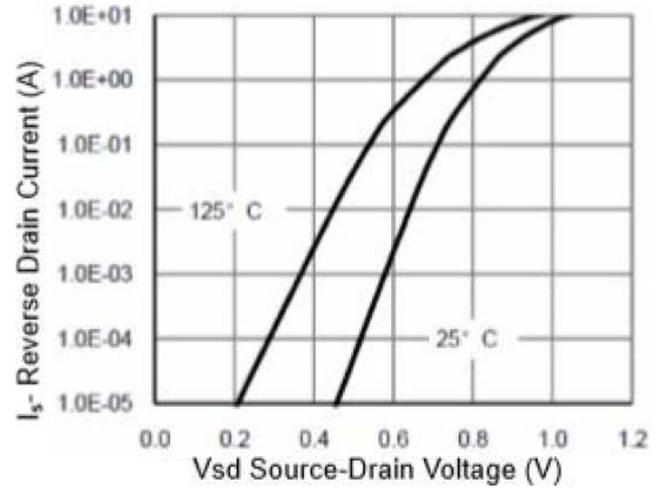


Figure 3: Power Dissipation

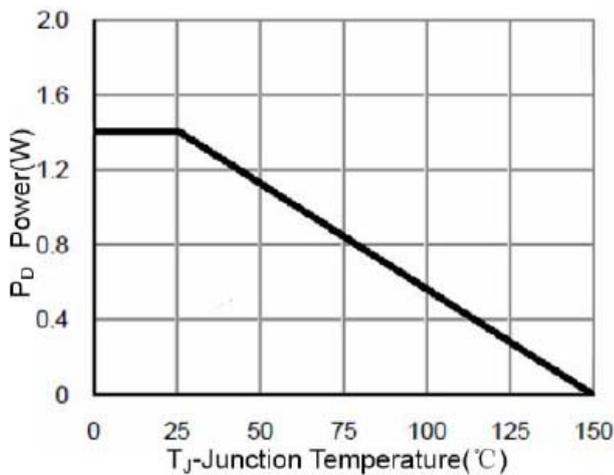


Figure 4: On-Resistance Drain-Source

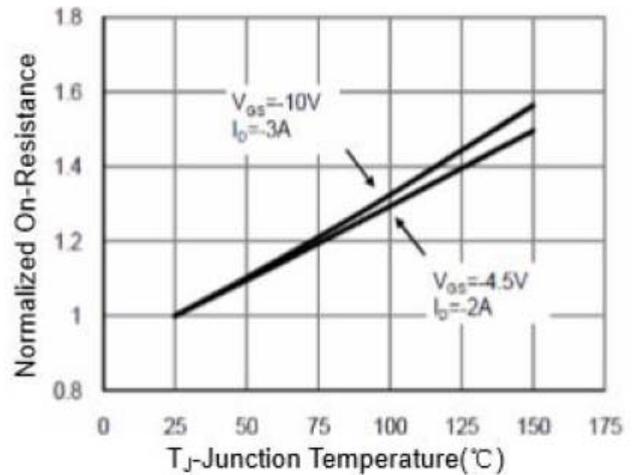


Figure 5: Drain Current.

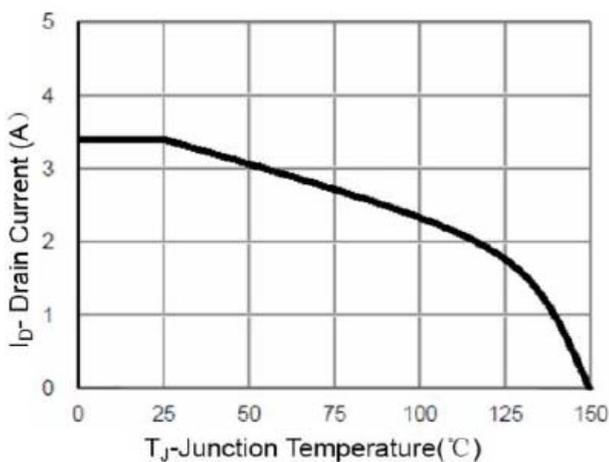


Figure 6: On-Resistance vs. Drain Current and Gate Voltage

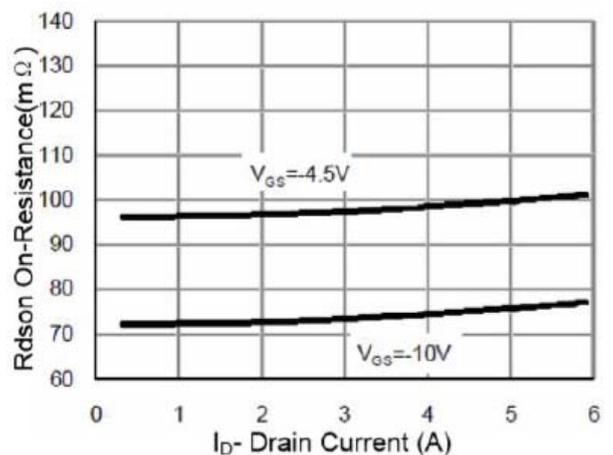


Figure 7: Gate Charge

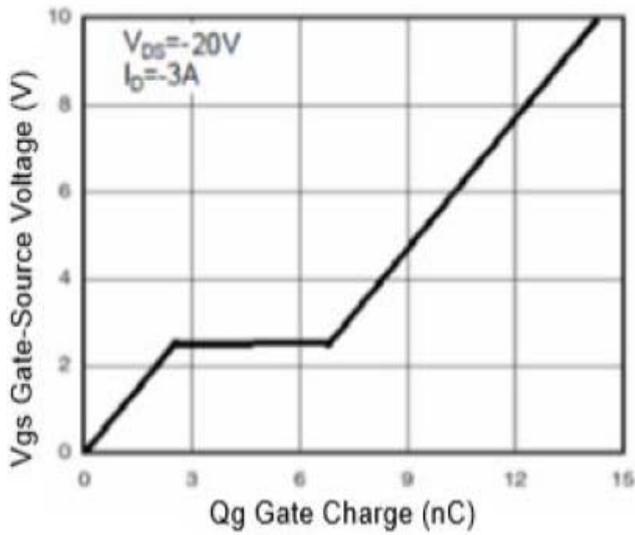


Figure 8: Maximum Safe Operating Area

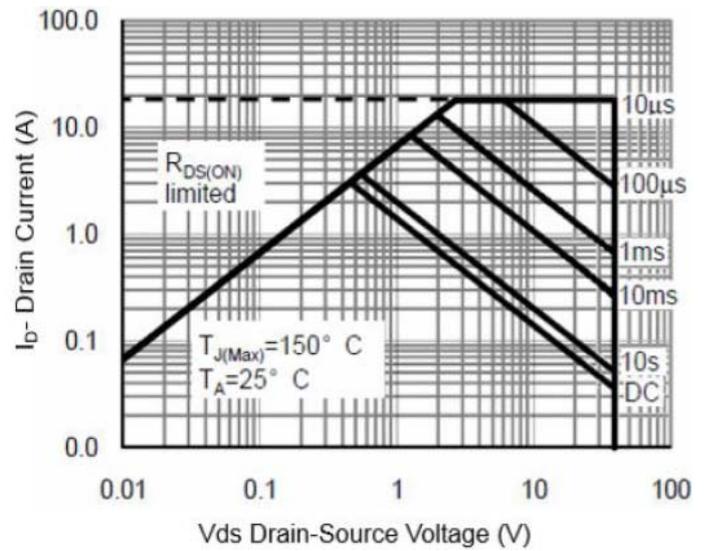


Figure 9: Capacitance Characteristics.

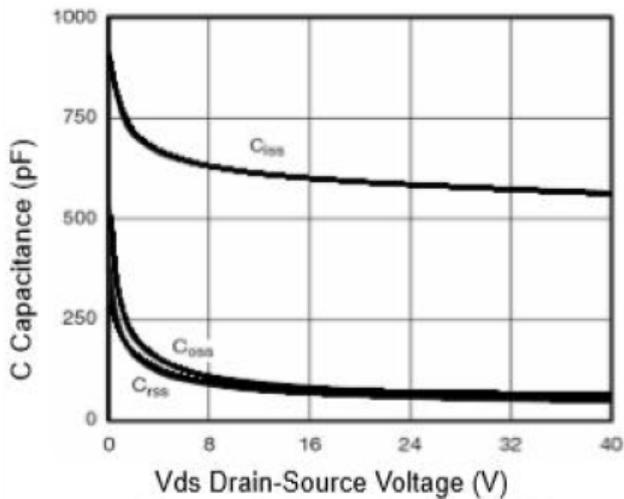


Figure 10: Switching Time Waveform

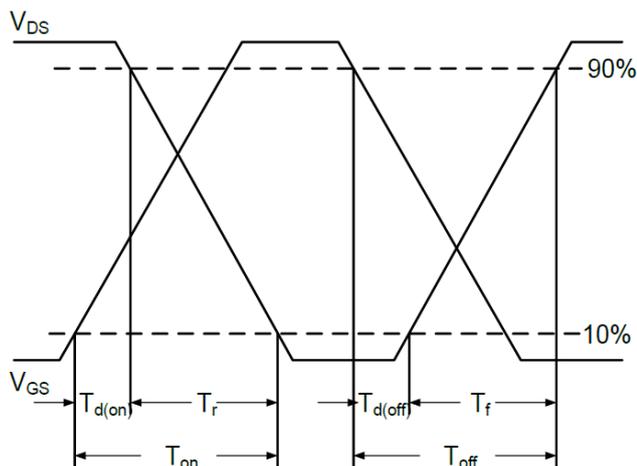
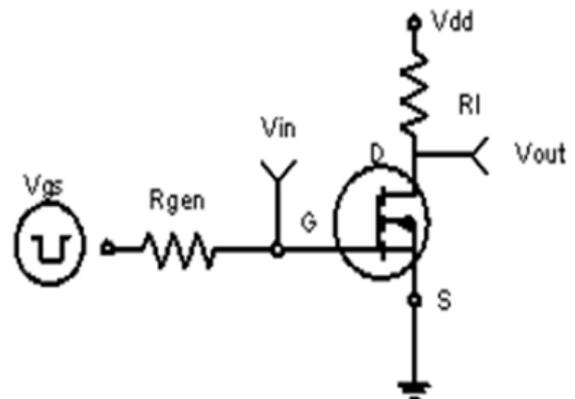
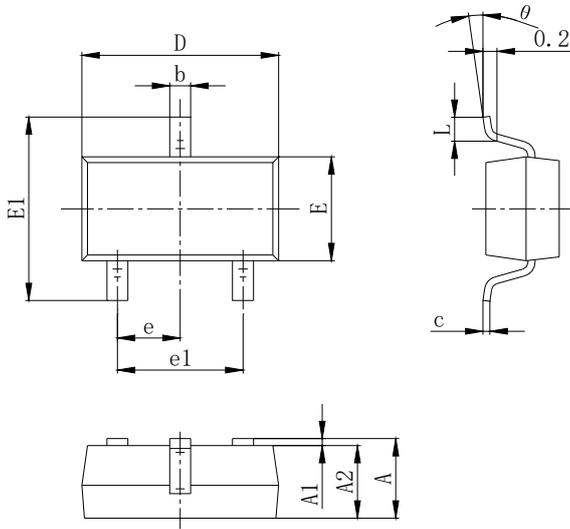


Figure 11: Switching Test Circuit



**PACKAGE MECHANICAL DATA**  
**SOT-23 Package Dimension**



Sym bo l	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.850	1.250	0.033	0.049
A1	0.000	0.130	0.000	0.005
A2	0.700	1.150	0.028	0.045
b	0.300	0.500	0.012	0.020
c	0.080	0.200	0.003	0.008
D	2.800	3.100	0.110	0.122
E	1.400	1.800	0.055	0.071
E1	2.600	3.000	0.102	0.118
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
$\theta$	0°	8°	0°	8°